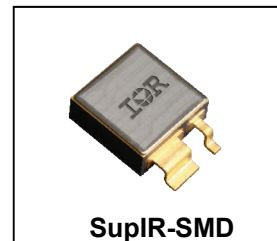


**RADIATION HARDENED
POWER MOSFET
SURFACE MOUNT (SupIR-SMD)**

130V, N-CHANNEL
REF: MIL-PRF-19500/684
R5 TECHNOLOGY

Product Summary

Part Number	Radiation Level	RDS(on)	I _D	QPL Part Number
IRHNS57163SE	100 kRads (Si)	0.0135Ω	75A*	JANSR2N7472U2A



Description

IR HiRel R5 technology provides high performance power MOSFETs for space applications. These devices have been characterized for Single Event Effects (SEE) with useful performance up to an LET of 80(MeV/(mg/cm²)). The combination of low R_{DS(on)} and low gate charge reduces the power losses in switching applications such as DC to DC converters and motor control. These devices retain all of the well established advantages of MOSFETs such as voltage control, fast switching and temperature stability of electrical parameters.

Features

- Single Event Effect (SEE) Hardened
- Ultra Low RDS(on)
- Low Total Gate Charge
- Simple Drive Requirements
- Hermetically Sealed
- Surface Mount
- Ceramic package
- Light Weight
- ESD Rating: Class 3B per MIL-STD-750, Method 1020

Absolute Maximum Ratings

Pre-Irradiation

Symbol	Parameter	Value	Units
I _{D1} @ V _{GS} = 12V, T _C = 25°C	Continuous Drain Current	75*	A
I _{D2} @ V _{GS} = 12V, T _C = 100°C	Continuous Drain Current	57	
I _{DM} @ T _C = 25°C	Pulsed Drain Current ①	300	
P _D @ T _C = 25°C	Maximum Power Dissipation	250	W
	Linear Derating Factor	2.0	W/°C
V _{GS}	Gate-to-Source Voltage	± 20	V
E _{AS}	Single Pulse Avalanche Energy ②	280	mJ
I _{AR}	Avalanche Current ①	75	A
E _{AR}	Repetitive Avalanche Energy ①	25	mJ
dv/dt	Peak Diode Recovery dv/dt ③	5.5	V/ns
T _J T _{STG}	Operating Junction and Storage Temperature Range	-55 to + 150	°C
	Package Mounting Surface Temperature	300 (for 5s)	
	Weight	3.3(Typical)	g

*Current is limited by package

For Footnotes refer to the page 2.

Electrical Characteristics @ T_j = 25°C (Unless Otherwise Specified)

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BV _{DSS}	Drain-to-Source Breakdown Voltage	130	—	—	V	V _{GS} = 0V, I _D = 1.0mA
ΔBV _{DSS} /ΔT _J	Breakdown Voltage Temp. Coefficient	—	0.17	—	V/°C	Reference to 25°C, I _D = 1.0mA
R _{DS(on)}	Static Drain-to-Source On-Resistance	—	—	0.0135	Ω	V _{GS} = 12V, I _{D2} = 57A ④
V _{GS(th)}	Gate Threshold Voltage	2.5	—	4.5	V	V _{DS} = V _{GS} , I _D = 1.0mA
G _{fs}	Forward Transconductance	39	—	—	S	V _{DS} = 15V, I _{D2} = 57A ④
I _{DSS}	Zero Gate Voltage Drain Current	—	—	10	μA	V _{DS} = 104V, V _{GS} = 0V
		—	—	25		V _{DS} = 104V, V _{GS} = 0V, T _J = 125°C
I _{GSS}	Gate-to-Source Leakage Forward	—	—	100	nA	V _{GS} = 20V
	Gate-to-Source Leakage Reverse	—	—	-100		V _{GS} = -20V
Q _G	Total Gate Charge	—	—	160	nC	I _{D2} = 75A
Q _{GS}	Gate-to-Source Charge	—	—	55		V _{DS} = 65V
Q _{GD}	Gate-to-Drain ('Miller') Charge	—	—	75		V _{GS} = 12V
t _{d(on)}	Turn-On Delay Time	—	—	35	ns	V _{DD} = 65V
t _r	Rise Time	—	—	125		I _{D2} = 75A
t _{d(off)}	Turn-Off Delay Time	—	—	80		R _G = 2.35Ω
t _f	Fall Time	—	—	50		V _{GS} = 12V
L _S + L _D	Total Inductance	—	4.0	—	nH	Measured from center of Drain pad to center of Source pad
C _{iss}	Input Capacitance	—	5020	—	pF	V _{GS} = 0V
C _{oss}	Output Capacitance	—	1490	—		V _{DS} = 25V
C _{rss}	Reverse Transfer Capacitance	—	116	—		f = 1.0MHz

Source-Drain Diode Ratings and Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I _S	Continuous Source Current (Body Diode)	—	—	75*	A	
I _{SM}	Pulsed Source Current (Body Diode) ①	—	—	300		
V _{SD}	Diode Forward Voltage	—	—	1.2	V	T _J = 25°C, I _S = 75A, V _{GS} = 0V ④
t _{rr}	Reverse Recovery Time	—	—	300	ns	T _J = 25°C, I _F = 75A, V _{DD} ≤ 50V
Q _{rr}	Reverse Recovery Charge	—	—	4.1	μC	di/dt = 100A/μs ④
t _{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L _S +L _D)				

* Current is limited by package

Thermal Resistance

Symbol	Parameter	Min.	Typ.	Max.	Units
R _{θJC}	Junction-to-Case	—	—	0.5	°C/W
R _{θJ-PCB}	Junction-to-PC Board (Soldered to 2" sq copper clad board)	—	1.6	—	°C/W

Footnotes:

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
- ② V_{DD} = 50V, starting T_J = 25°C, L = 0.1mH, Peak I_L = 75A, V_{GS} = 12V
- ③ I_{SD} ≤ 75A, di/dt ≤ 280A/μs, V_{DD} ≤ 130V, T_J ≤ 150°C
- ④ Pulse width ≤ 300 μs; Duty Cycle ≤ 2%
- ⑤ Total Dose Irradiation with V_{GS} Bias. 12 volt V_{GS} applied and V_{DS} = 0 during irradiation per MIL-STD-750, Method 1019, condition A.
- ⑥ Total Dose Irradiation with V_{DS} Bias. 104 volt V_{DS} applied and V_{GS} = 0 during irradiation per MIL-STD-750, Method 1019, condition A.

Radiation Characteristics

IR HiRel Radiation Hardened MOSFETs are tested to verify their radiation hardness capability. The hardness assurance program at IR HiRel is comprised of two radiation environments. Every manufacturing lot is tested for total ionizing dose (per notes 5 and 6) using the TO-3 package. Both pre- and post-irradiation performance are tested and specified using the same drive circuitry and test conditions in order to provide a direct comparison.

Table1. Electrical Characteristics @ T_j = 25°C, Post Total Dose Irradiation ⑤⑥

Symbol	Parameter	1000 kRads (Si)		Units	Test Conditions
		Min.	Max.		
BV _{DSS}	Drain-to-Source Breakdown Voltage	130	—	V	V _{GS} = 0V, I _D = 1.0mA
V _{GS(th)}	Gate Threshold Voltage	2.0	4.5	V	V _{DS} = V _{GS} , I _D = 1.0mA
I _{GSS}	Gate-to-Source Leakage Forward	—	100	nA	V _{GS} = 20V
I _{GSS}	Gate-to-Source Leakage Reverse	—	-100	nA	V _{GS} = -20V
I _{DSS}	Zero Gate Voltage Drain Current	—	10	μA	V _{DS} = 104V, V _{GS} = 0V
R _{DS(on)}	Static Drain-to-Source ④ On-State Resistance (TO-3)	—	0.014	Ω	V _{GS} = 12V, I _{D2} = 57A
R _{DS(on)}	Static Drain-to-Source ④ On-State Resistance (SupIR-SMD)	—	0.0135	Ω	V _{GS} = 12V, I _{D2} = 57A
V _{SD}	Diode Forward Voltage ④	—	1.2	V	V _{GS} = 0V, I _S = 75A

IR HiRel radiation hardened MOSFETs have been characterized in heavy ion environment for Single Event Effects (SEE). Single Event Effects characterization is illustrated in Fig. a and Table 2.

Table 2. Typical Single Event Effect Safe Operating Area

LET (MeV/(mg/cm ²))	Energy (MeV)	Range (μm)	VDS (V)				
			@VGS=0V	@VGS=-5V	@VGS=-10V	@VGS=-15V	@VGS=-20V
38 ± 5%	300 ± 7.5%	38 ± 7.5%	130	130	130	130	130
61 ± 5%	330 ± 7.5%	31 ± 10%	130	130	130	100	50
84 ± 5%	350 ± 10%	28 ± 7.5%	130	120	30	-	-

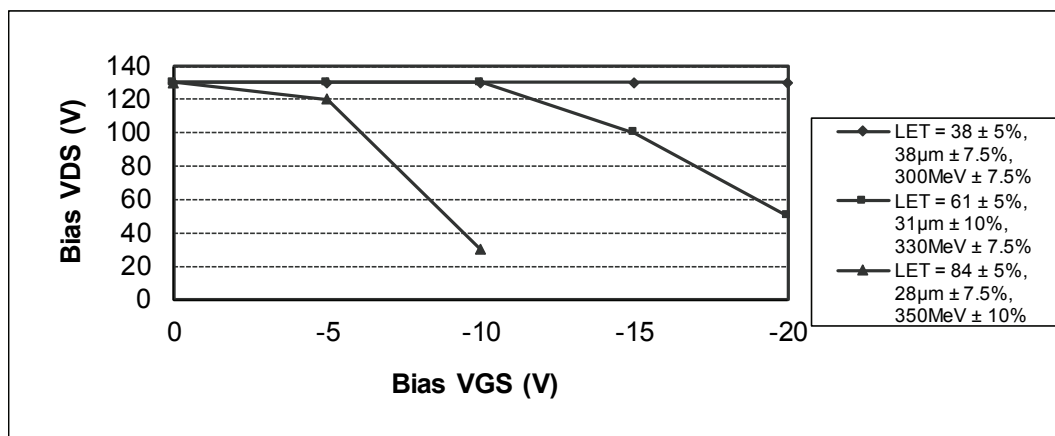


Fig a. Typical Single Event Effect, Safe Operating Area

For Footnotes, refer to the page 2.

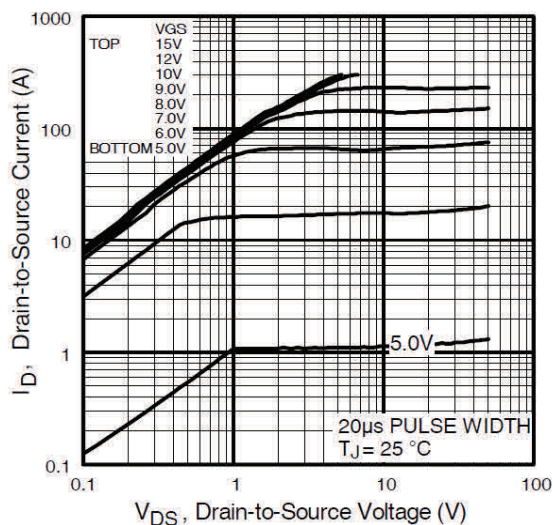


Fig 1. Typical Output Characteristics

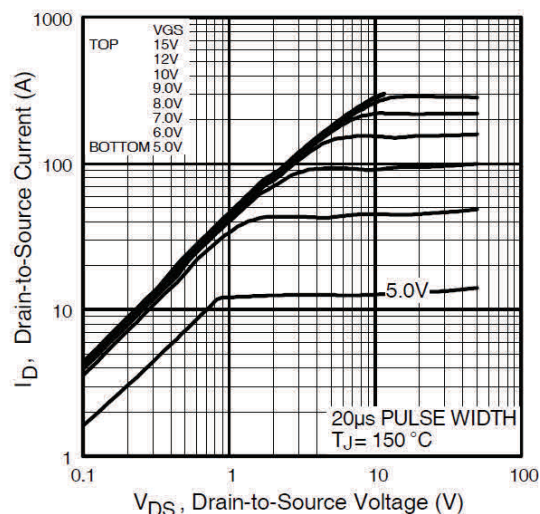


Fig 2. Typical Output Characteristics

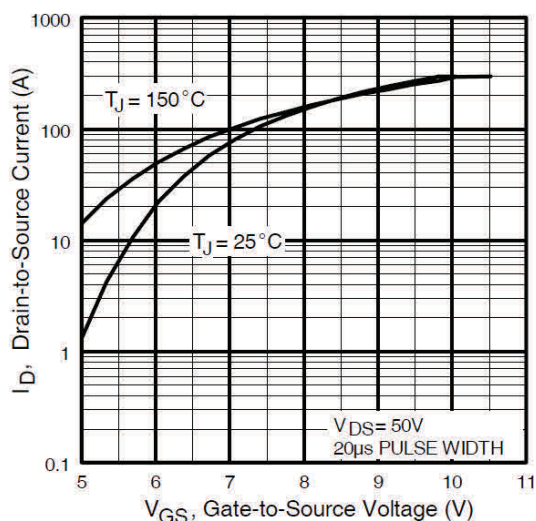


Fig 3. Typical Transfer Characteristics

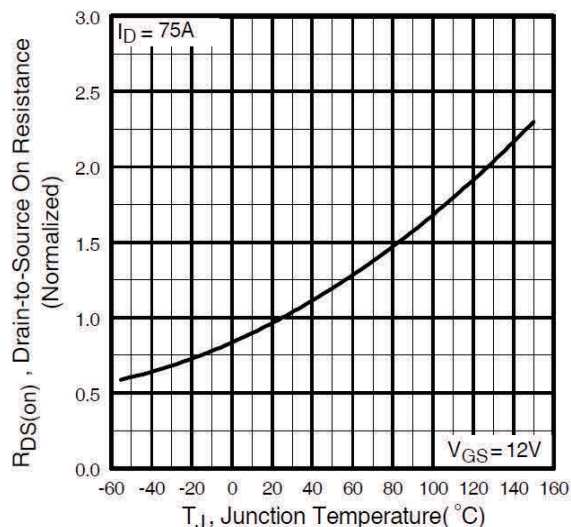


Fig 4. Normalized On-Resistance Vs. Temperature

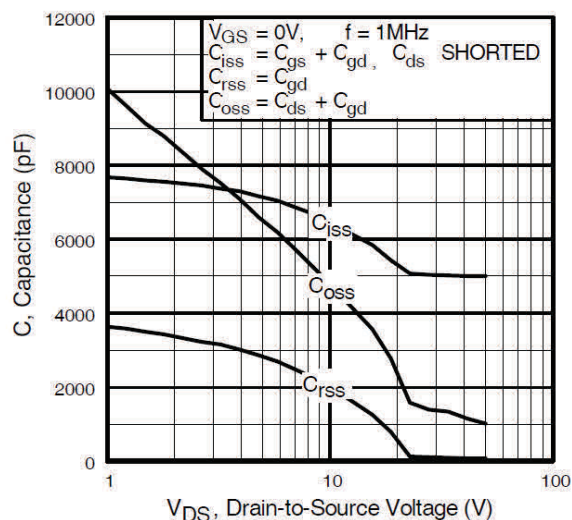


Fig 5. Typical Capacitance Vs.
Drain-to-Source Voltage

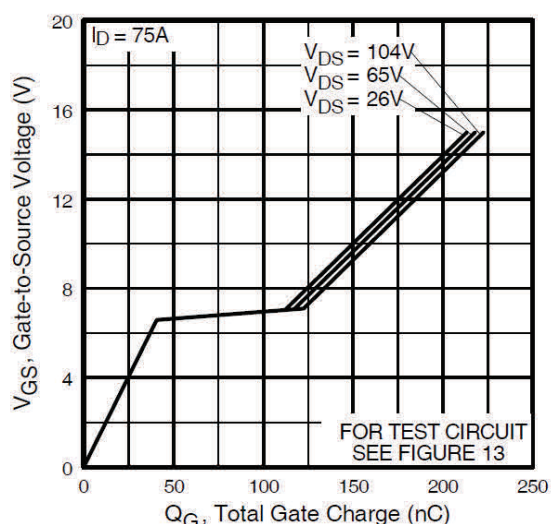


Fig 6. Typical Gate Charge Vs.
Gate-to-Source Voltage

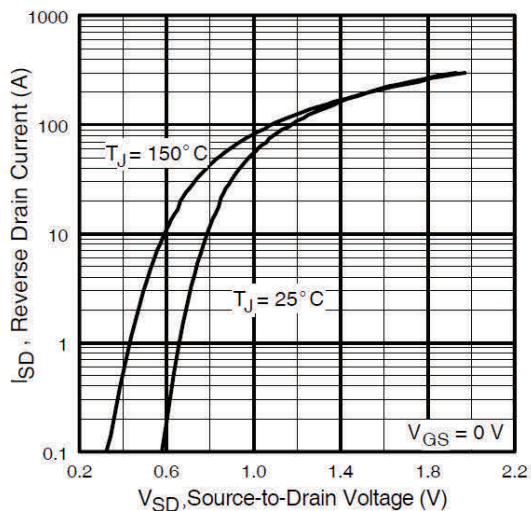


Fig 7. Typical Source-Drain Diode Forward Voltage

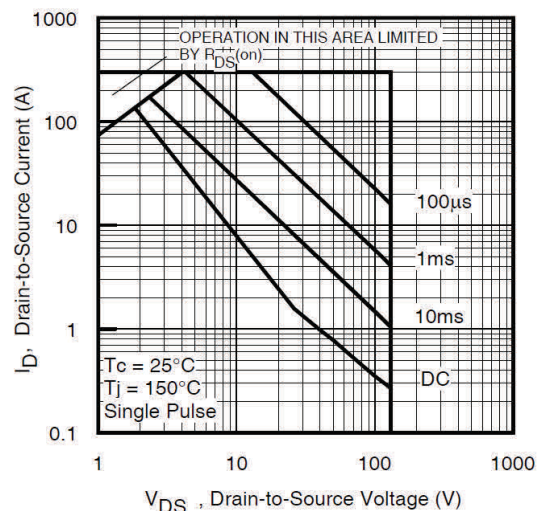


Fig 8. Maximum Safe Operating Area

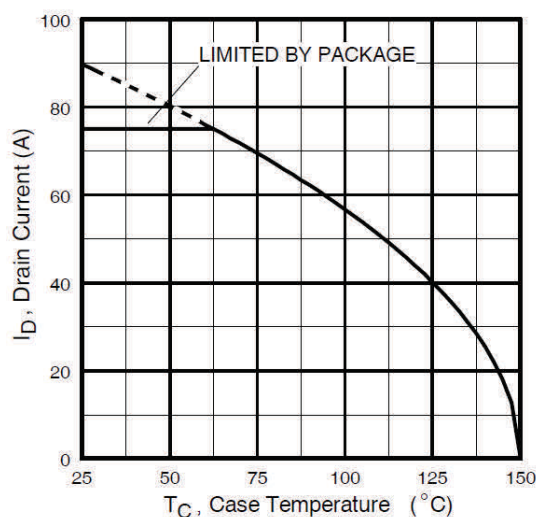


Fig 9. Maximum Drain Current Vs. Case Temperature

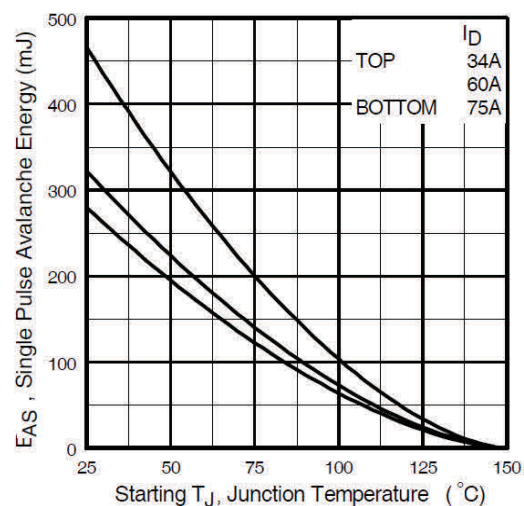


Fig 10. Maximum Avalanche Energy Vs. Drain Current

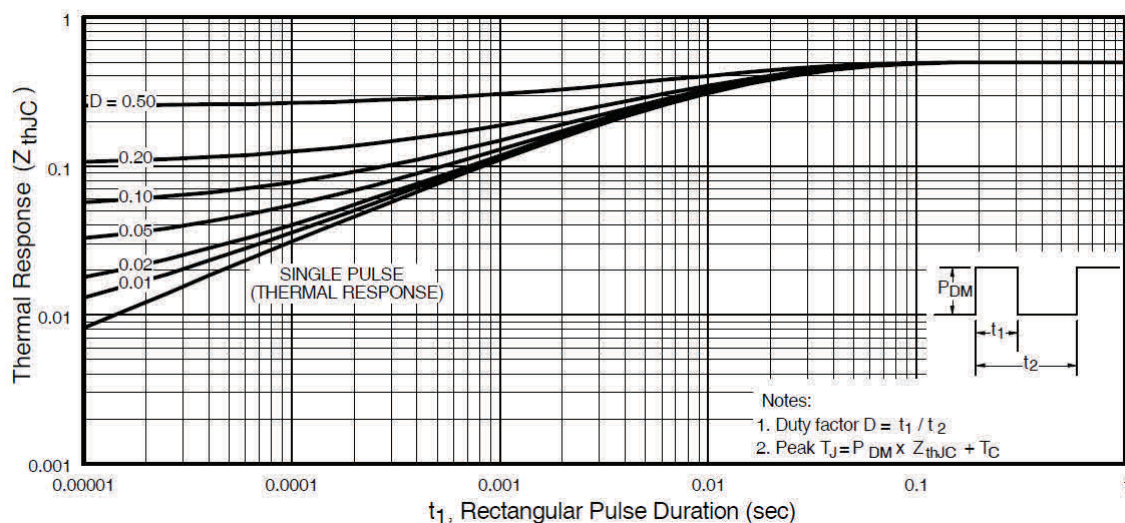


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

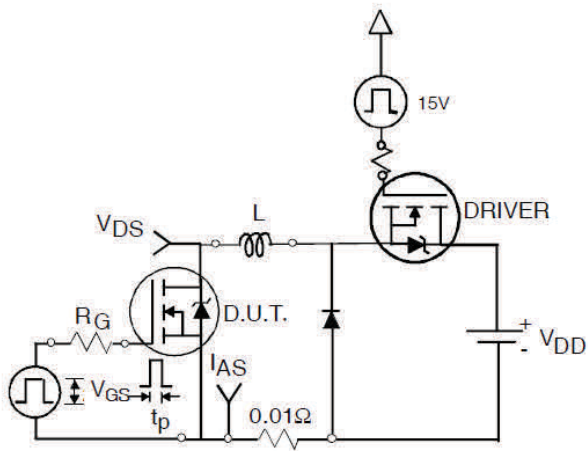


Fig 12a. Unclamped Inductive Test Circuit

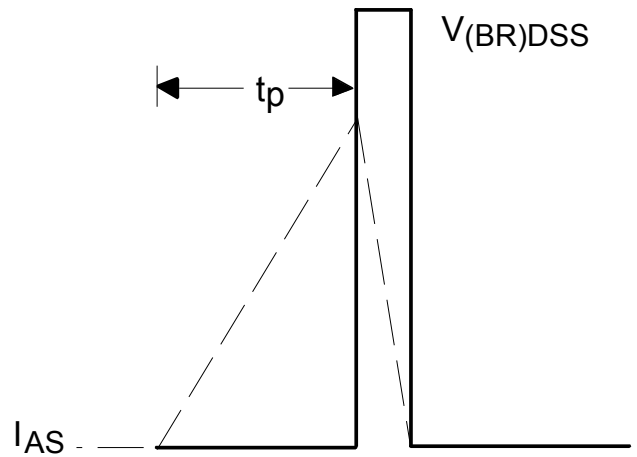


Fig 12b. Unclamped Inductive Waveforms

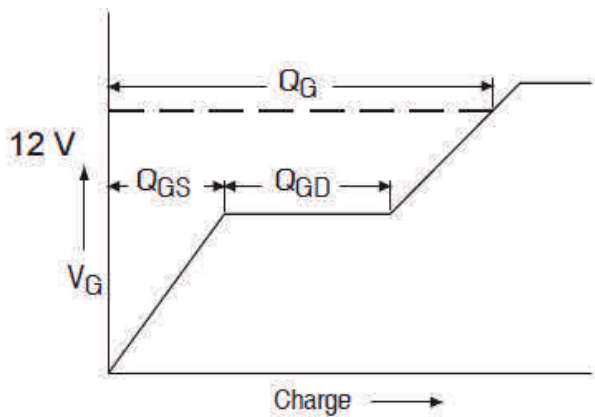


Fig 13a. Gate Charge Waveform

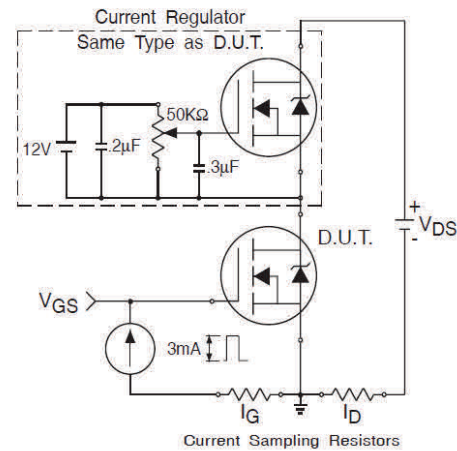


Fig 13b. Gate Charge Test Circuit

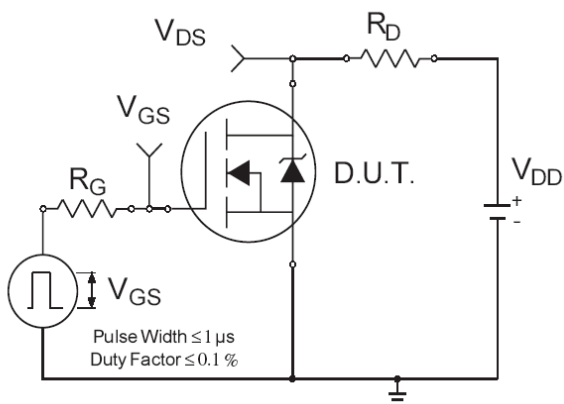


Fig 14a. Switching Time Test Circuit

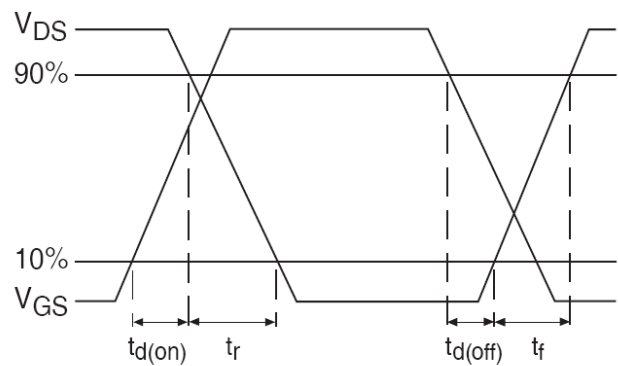


Fig 14b. Switching Time Waveforms

Top View Dimensions:

- Overall Width: 13.61 [.536] / 13.31 [.524]
- Overall Height: 18.03 [.710] REF.
- Pin Pitch (Left): 2.03 [.080] / 1.78 [.070]
- Pin Pitch (Right): 5.21 [.205] / 4.95 [.195]
- Pin Width (Left): 3.43 [.135] / 3.18 [.125]
- Pin Width (Right): 1.40 [.055] / 1.14 [.045]
- Lead Length (Left): .127 [.005] TYP.
- Lead Length (Right): 2.16 [.085] / 1.91 [.075]
- Lead Spacing (Bottom): .76 [.030] MIN. IN BETWEEN METALIZATION

Side View Dimensions:

- Package Height: 6.60 [.260] MAX.
- Lead Angle: 4° MAX.
- Lead Thickness: .38 [.015] / .13 [.005]
- Lead Width (Left): .43 [.017] / .33 [.013]
- Lead Width (Right): 1.27 [.050] / 1.02 [.040]
- Lead Spacing (Bottom): 0 - .07 [.003] / +.10 [.004]

Bottom View Dimensions:

- Overall Width: 12.83 [.505] / 12.57 [.495]
- Overall Height: 11.05 [.435] / 10.80 [.425]
- Pin Pitch (Left): 2.11 [.083] / 1.85 [.073]
- Pin Pitch (Right): 9.02 [.355] / 8.76 [.345]
- Pin Width (Left): 6.60 [.260] / 6.35 [.250]
- Pin Width (Right): 3.30 [.130] / 3.05 [.120]
- Pin Length (Left): 1.02 [.040] MIN.
- Pin Length (Right): 1.65 [.065] / 1.40 [.055]

PAD ASSIGNMENTS

- 1 = DRAIN
- 2 = GATE
- 3 = SOURCE

NOTES:

- FOR REFERENCE ONLY: LEAD LENGTH AFTER TIE-BAR CUT MUST .300 ±.015 FROM THE FROM PACKAGE BODY.
- BEND AND TRIM LEADS USING EQUIPMENT ASSET #03493.

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